

CDCVF111 1:9 DIFFERENTIAL LVPECL CLOCK DRIVER

SCAS670B – SEPTEMBER 2001 – REVISED JUNE 2002

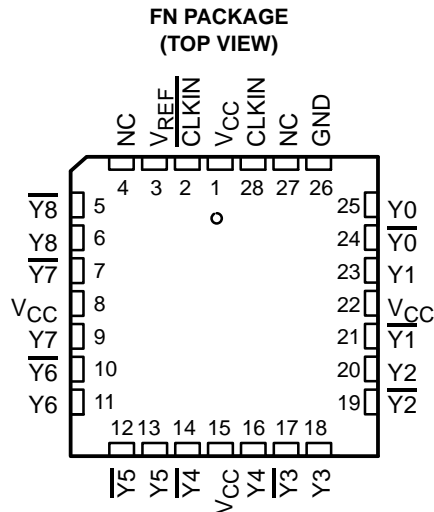
- Low-Output Skew for Clock-Distribution Applications
- Differential Low-Voltage Pseudo-ECL (LVPECL) Compatible Inputs and Outputs
- Distributes Differential Clock Inputs to Nine Differential Clock Outputs
- Output Reference Voltage (V_{REF}) Allows Distribution From a Single-Ended Clock Input
- Packaged In a 28-Pin Plastic Chip Carrier

description

The differential LVPECL clock-driver circuit distributes one pair of differential LVPECL clock inputs (\overline{CLKIN} , $CLKIN$) to nine pairs of differential clock (Y , \overline{Y}) outputs with minimum skew for clock distribution. It is specifically designed for driving 50- Ω transmission lines.

The V_{REF} output can be strapped to the \overline{CLKIN} input for a single-ended $CLKIN$ input.

The CDCVF111 is characterized for operation from -40°C to 85°C .



NC – No internal connection

FUNCTION TABLE

INPUTS		OUTPUTS	
$CLKIN$	\overline{CLKIN}	Y_n	\overline{Y}_n
X	X	L	H
L	H	L	H
H	L	H	L
L	V_{REF}	L	H
H	V_{REF}	H	L
V_{REF}	L	H	L
V_{REF}	H	L	H



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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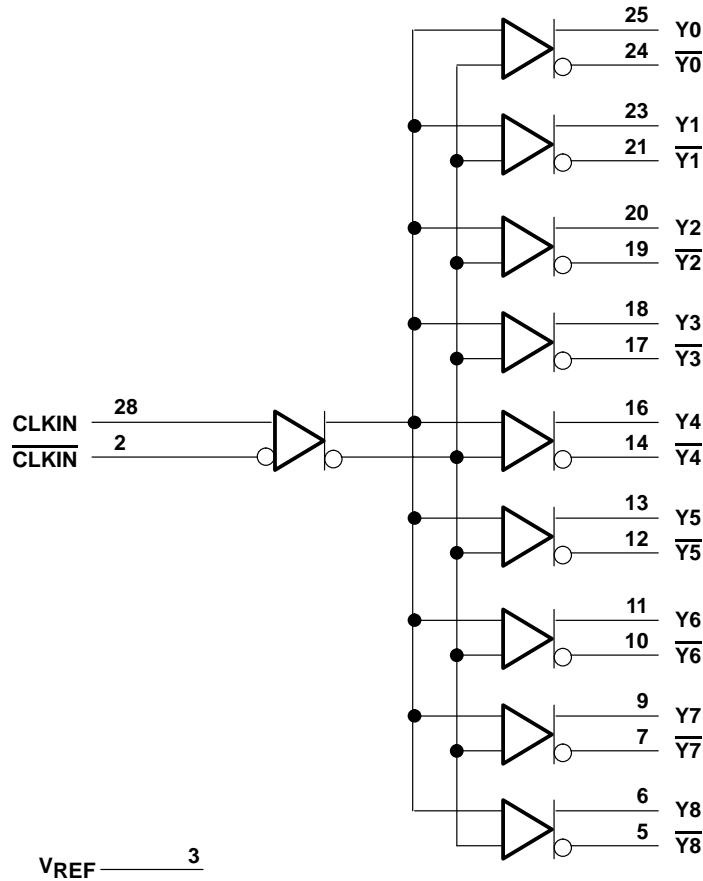
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CDCVF111

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SCAS670B – SEPTEMBER 2001 – REVISED JUNE 2002

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	-0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	-0.5 V to $V_{CC} + 0.5$ V
Output voltage range, V_O (see Note 1)	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	-18 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	-18 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	-50 mA
Continuous current through V_{CC} or GND	± 80 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2)	525 mW
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002.



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SCAS670B – SEPTEMBER 2001 – REVISED JUNE 2002

recommended operating conditions

		MIN	MAX	UNIT	
V_{CC}	Supply voltage	3	3.6	V	
V_{IH}	High-level input voltage	$V_{CC} = 3\text{ V to }3.6\text{ V}$	$V_{CC}-1.165$	$V_{CC}-0.88$	V
		$V_{CC} = 3.3\text{ V}$	2.135	2.42	V
V_{IL}	Low-level input voltage	$V_{CC} = 3\text{ V to }3.6\text{ V}$	$V_{CC}-1.81$	$V_{CC}-1.475$	V
		$V_{CC} = 3.3\text{ V}$	1.49	1.825	V
T_A	Operating free-air temperature	-40	85	°C	
f_{clock}	Input frequency		650	MHz	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	MAX	UNIT
V_{REF}	$V_{CC} = 3\text{ V to }3.6\text{ V}$	$I_{REF} = 100\ \mu\text{A}$	$V_{CC}-1.38$	$V_{CC}-1.26$	V
	$V_{CC} = 3.3\text{ V}$		1.92	2.04	
V_{OH}	$V_{CC} = 3\text{ V to }3.6\text{ V}$, $T_A = 0^\circ\text{C to }85^\circ\text{C}$, $f_{(max)} = 650\text{ MHz}$		$V_{CC}-1.12$	$V_{CC}-0.83$	V
	$V_{CC} = 3\text{ V to }3.6\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$, $f_{(max)} = 650\text{ MHz}$		$V_{CC}-1.15$	$V_{CC}-0.83$	
	$V_{CC} = 3.3\text{ V}$		2.275	2.42	
V_{OL}	$V_{CC} = 3\text{ V to }3.6\text{ V}$, $T_A = 0^\circ\text{C to }85^\circ\text{C}$, $f_{(max)} = 650\text{ MHz}$		$V_{CC}-1.86$	$V_{CC}-1.49$	V
	$V_{CC} = 3\text{ V to }3.6\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$, $f_{(max)} = 650\text{ MHz}$		$V_{CC}-1.86$	$V_{CC}-1.52$	
	$V_{CC} = 3.3\text{ V}$		1.49	1.68	
I_I	$V_I = 2.4\text{ V}$,	$V_{CC} = 3.6\text{ V}$		150	μA
I_{CC} (Internal)	$I_O = 0$,	$V_{CC} = 3.6\text{ V}$		100	mA

switching characteristics over recommended operating free-air temperature range, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (see Figure 1 and Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
t_{PLH}	CLKIN, $\overline{\text{CLKIN}}$	Y, \overline{Y}	450	600	ps
t_{PHL}					
$t_{sk(o)}$		Y, \overline{Y}		50	ps
$t_{sk(pr)}$		Y, \overline{Y}		150	ps
t_r		Y, \overline{Y}	200	600	ps
t_f					

CDCVF111

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SCAS670B – SEPTEMBER 2001 – REVISED JUNE 2002

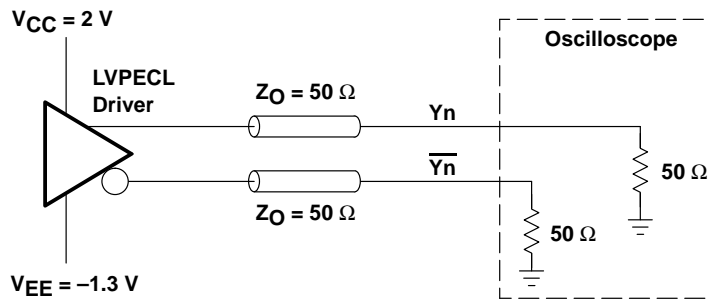
ESD information

ESD MODELS	LIMIT
Human Body Model (HBM)	2.0 kV
Machine Model (MM)	200 V
Charge Device Model (CDM)	2.0 kV

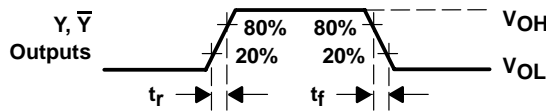
thermal information

CDCVF111 28-PIN PLCC		THERMAL AIR FLOW (CFM)				UNIT
		0	150	250	500	
R θ JA	High K	48	44	42	39	°C/W
R θ JA	Low K	70	58	52	46	°C/W
R θ JC	High K	22				°C/W
R θ JC	Low K	28				°C/W

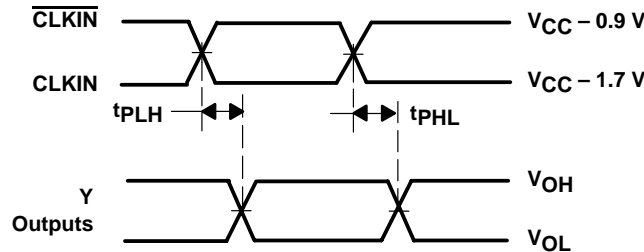
PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT (See Note B)



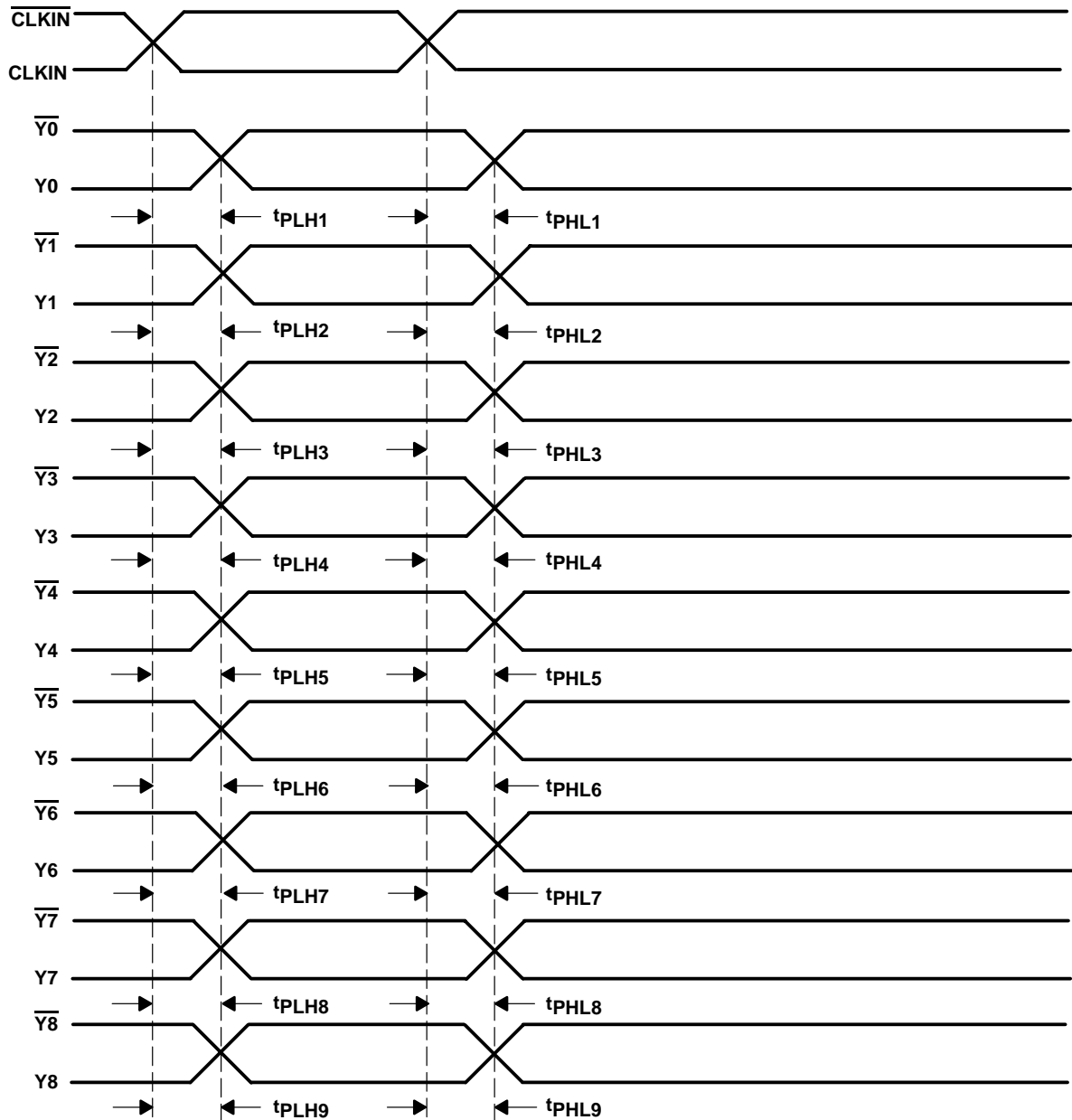
VOLTAGE WAVEFORMS
RISE AND FALL TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

- NOTES: A. All input pulses are supplied by generators having the following characteristics: PRR \leq 45 MHz, $Z_O = 50 \Omega$, $t_r \leq 1$ ns, $t_f \leq 1$ ns.
 B. For additional signal interface, see the *Interfacing Between LVPECL, LVDS, and CML* application note, Literature Number SCAA056.

Figure 1. Load Circuit and Voltage Waveforms



- NOTES: A. Output skew, $t_{sk(o)}$, is calculated as the greater of:
- The difference between the fastest and slowest t_{PLHn} ($n = 1, 2, \dots, 9$)
 - The difference between the fastest and slowest t_{PHLn} ($n = 1, 2, \dots, 9$)
- B. Process skew, $t_{sk(pr)}$, is calculated as the greater of:
- The difference between the fastest and slowest t_{PLHn} ($n = 1, 2, \dots, 9$)
 - The difference between the fastest and slowest t_{PHLn} ($n = 1, 2, \dots, 9$) across multiple devices
- C. For additional information on skew and propagation delay parameters, see the *Defining Skew, Propagation Delay, Phase-Offset (Phase Error)* application note, literature number SCAA055.

Figure 2. Waveforms for Calculation of $t_{sk(o)}$, $t_{sk(pr)}$

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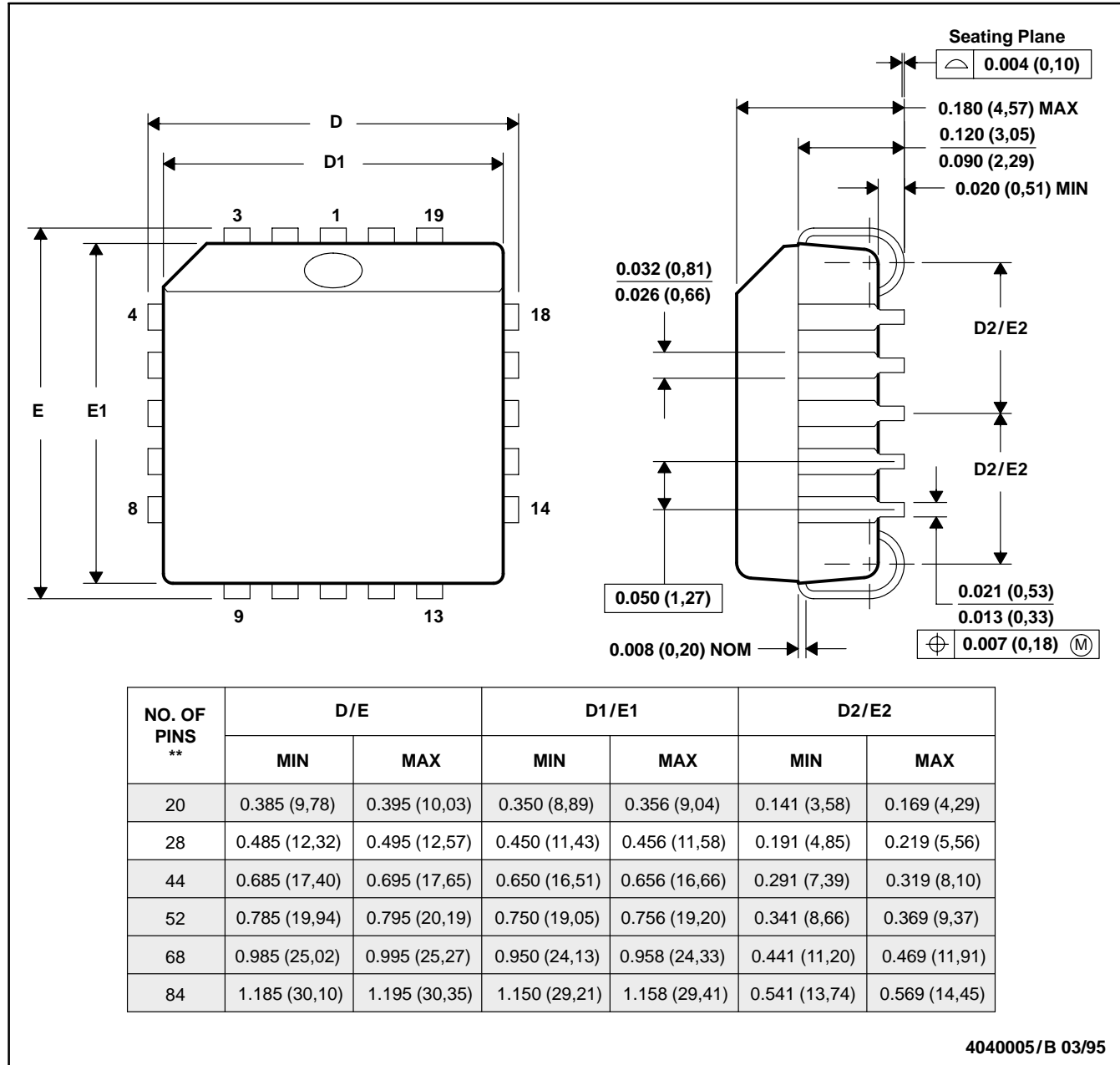
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MECHANICAL DATA

FN (S-PQCC-J**)

PLASTIC J-LEADED CHIP CARRIER

20 PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-018

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CDCVF111FN	ACTIVE	PLCC	FN	28	37	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CDCVF111FNG4	ACTIVE	PLCC	FN	28	37	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CDCVF111FNR	ACTIVE	PLCC	FN	28	750	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CDCVF111FNRG4	ACTIVE	PLCC	FN	28	750	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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